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NATURE OF CONVEYANCE:			ASSIGNMENT				
CONVEYING PARTY	DATA						
Na			lame	Execution Date			
Min-Ho O				07/23/2008			
Jong-Ho LEE				07/23/2008			
Eun-Chul AHN				07/23/2008			
Pyoung-Wan KIM				07/23/2008			
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State/Country:	KOREA, DEMOCRATIC PEOPLE'S REPUBLIC OF						
PROPERTY NUMBER	S Total: 1						
Property Type			Number				
Application Number: 1212		12121	490				
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ATTORNEY DOCKET NUMBER:			9898-673				
NAME OF SUBMITTER:			Hosoon Lee				
Total Attachments: 2 source=Assignment#p source=Assignment#p	+						
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JUN-09-2008 15:54	Marger Johnson McCollom	5032744622 P	.007
		PATENT APPLICATION Docket No.: 9898-673 Client Ref. No.: SS-30660-US	2
	ASSIGNMENT		
	U.S.A. Patent Application Sole or Joint For Inventions Made Outside U. Executed With Application		
In consideration of the s to each of the undersigne	um of Ten Dollars (10.00) and other good	and valuable considerations paid	
 Min-He O Jong-Ho LEE Eun-Chul AHN Pyoung-Wan KIM 	.:		
	X if continued on separate pa	ġ ¢	
the receipt and sufficiency assign(s) and transfer(s) u	y of which are hereby acknowledged by the new ledged by the second s	to undersigned who hereby sell(s),	
SAMSUNG ELECTRON 416 MAETAN 3-DONG, REPUBLIC OF KOREA	VOINCTONG OF AVAILAND A	KYUNGKI-DO	
(hereinafter designated "A defined in 35 USC §100, f	SSIGNEE") the entire right, title and into or the United States of America, the inves	rest in and to the invention as ation entitled:	
SEMICONDUCT	OR PACKAGE USING CHIP-EMB SUBSTRATE	EDDED INTERPOSER	
in and to any and all divisic patents and the undersigned Commissioner of Patents to ASSIGNEE, its successors	r Letters Patent of the United States of As 2/121,490 has been executed even date he onals, continuations, substitutes, and reiss i hereby authorizes and requests the Unite issue said Letters Patent to the said ASS assigns and legal representatives; the une opplication shall hereafter act on behalf of	newith by the undersigned, and ues thereof; and all resulting of States Assistant IGNEE, for its interest as	
And the undersigned hereby	agrees to testify and execute any papers	•	

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